

To qualify, please note the following:

1. All manufacturing related products, materials and equipment submitted must be introduced and offered for sale between 1 January 2009 and 31 December 2009 in Asia.
2. All sections must be completed. Incomplete entries will be disqualified by the judges.
3. All entries must be accompanied by **this form and payment**. **Product descriptions submitted must be in both English and Simplified Chinese.**
4. Entries must reach us by **26 February 2010**. Please see Section F for submission guidelines.

为免失去参评资格, 请注意以下事项:

1. 所有参评产品必须为2009年1月1日至2009年12月31日期间在亚洲地区公开发布或销售。
2. 报名表内所有内容必须填写完整, 否则将被取消参评资格。
3. 所有参评产品必须附有此表, 产品说明必须包含中英文两种文本。
4. 报名截至日期为2010年2月26日。具体提交方式请参阅报名表的F部分。

A. COMPANY INFORMATION • 公司信息

Company: 公司:	
Submitted by: 报名联系人:	
Job Title / Email: 职位/邮箱:	
Billing Contact: 付款联系人:	
Job Title: 职位:	
Mailing Address: 通讯地址:	
Postal Code: 邮编:	
City: 城市:	
Country: 国家:	
Tel / Mobile: 电话 / 手机:	
Fax: 传真:	
Email: 邮箱:	

B. Award Categories • 奖项类别

Entry fee: USD500 per category
报名费: \$500美元/每项

✓	<u>Categories</u>	<u>奖项类别</u>
	Adhesive/Coating/Encapsulating Materials	胶粘/涂覆/灌封材料
	Alternative Energy - Production Equipment	可再生能源生产设备
	Alternative Energy - Products/Materials	可再生能源生产材料
	Assembly Line Systems/Equipment	组装生产线系统/设备
	Cleaning Equipment	清洗设备
	Cleaning Materials	清洗材料
	Dispensing Systems/Equipment	点涂系统/设备
	Environmentally Friendly Production Equipment	环保生产设备
	Environmentally Friendly Products/Materials	环保产品/材料
	Inspection Equipment - AOI	检测设备—AOI
	Inspection Equipment - X-ray	检测设备—X-Ray
	Manual Soldering Equipment	手工焊接设备
	Pick and Place Systems/Equipment (Low/Medium Volume)	贴片系统/设备 (中小批量)
	Pick and Place Systems/Equipment (High Volume)	贴片系统/设备 (大批量)
	Programming Systems	编程系统
	Reflow Soldering Equipment	回流焊接设备
	Repair/Rework Equipment	返修/返工设备
	Stencil & Screen Printing Systems/Equipment	印刷系统/设备
	Process Control Systems	工艺控制系统
	Selective Soldering Equipment	选择性焊接设备
	Software/Production Management Systems	软件/生产管理系统
	Soldering Materials	焊接材料
	Test Systems/Equipment	测试系统/设备
	Wave Soldering Equipment	波峰焊设备

C. PRODUCT INFORMATION (Up to 250 words in English & Simplified Chinese)

产品介绍 (请不超过250字)

1. Your submission must cover the following aspects of your product:

您所提交介绍须包括以下内容:

- Innovation - 创新性
- Cost effectiveness - 性价比
- Speed/Throughput improvements - 速度/产能改善情况
- Quality Contribution - 质量贡献
- Ease of use - 易用性
- Maintainability and repairability - 可维护性与可维修性
- Technology advancement - 技术先进性

Please submit the information on a separate sheet. 请使用单独附件提供相关信息。

2. Other required documents 其他必须文档

- A PDF or word file on technical specifications documenting a service program along with appropriate customer approval letter.
技术规格描述的PDF或Word文档, 操作说明以及客户认可信
- High resolution product image (300 dpi and above)
高清晰度产品照片 (300dpi或以上)
- Company name and standard product or service description to be used for judging and award purposes.
公司名称及标准产品或服务名称以备评选和颁奖使用

D. TERMS & CONDITIONS • 注意事项

1. All payments made are not refundable. 所有的款项均不予退还。
2. Winners will not be notified before the awards ceremony. 获奖者将不会收到提前通知
3. Entrants will receive a written invitation to the EM Asia Innovation Awards Presentation Ceremony.
所有参评者将获得EM Asia创新奖颁奖典礼的书面邀请。
4. The EM Asia Innovation Awards is not affiliated to any advertising program in any manner.
EM Asia创新奖不带有任何广告性质。
5. Winners are judged solely upon the merits of their product submissions.
纯粹根据产品的性能评出获奖者。
6. We reserve the right to not award a winner in a given category.
我们保留在某一奖项无获奖者的权力。
7. Materials submitted for competition will become the property of EM Asia and will not be returned.
提交材料归EM Asia所有, 不予退还。
8. Entries must be postmarked or emailed to us by 26 February 2010.
参评产品报名表必须在2010年2月26日前发出。

Official Entry Form • 报名表

Closing Date: 26 February 2010

报名截至日期: 2010年2月26日

F. PAYMENT 付款方式

1. Cheque/Banker's Draft

I enclose a cheque/banker's draft for USD ____ made payable to Ten Alps Communications Asia Pte Ltd.

随信以支票/银行汇票支付 Ten Alps Communications Asia Pte Ltd ____美元。

Cheque/Bank Draft Number:
支票/银行汇票号:

Name of Bank 银行名称: The Hongkong and Shanghai Banking Corporation Limited

Bank Address 银行地址: 21 Collyer Quay, #06-01 HSBC Building, Singapore 049320

Account Number 帐号: 152-493623-001 (SGD A/C), 260-690383-178 (USD A/C), 260-690383-179 (GBP A/C)

2. Credit Card

Please debit USD from my Visa/Mastercard/Amex card

以Visa /Mastercard/Amex 信用卡支付 美元

Card Number 卡号:

Card Expiry Date 卡有效期:

Card Holder's Name 持卡人姓名:

Signature 签名:

Date 日期:

G. SUBMISSION GUIDELINES 报名方式

Please submit items A, B, C, D and E via email, CD or diskette to:
请以邮件、CD或磁盘形式提交报名表A、B、C、D及E部分至:

Ten Alps Communications Asia Pte Ltd
The Signature, 51 Changi Business Park Central 2, #07-01
Singapore 486066
Attention: Laura Low, Marketing Executive
Email: laura.low@rbi-asia.com

If you have included any of the following, please tick the appropriate items:
若含有其他附件, 请选择以下形式:

- CD-ROM 光盘
- Diskette 磁碟
- Print copies of product information and other required documents
产品介绍和其他文档的印刷资料



Official Entry Form • 报名表

Closing Date: 26 February 2010
报名截至日期: 2010年2月26日

H. CERTIFICATION 证明

We certify that the information submitted in this entry form is true and its contents have been approved by authorized personnel for submission to the Electronics Manufacturing Asia Innovation Awards 2010. We agree to the terms and conditions of the Awards and understand the information submitted here may be made known to the public. We also understand should the information given here be proven untrue, this entry may be disqualified, even if it has been selected as a winner.

我们保证报名表所提交的信息是真实的，所提交内容已被授权允许提交给2010 EM Asia创新奖评选。我们赞同创新奖评选的条件和规则，并知道所提交的材料可能将向公众透漏。我们也充分理解以下行为，即：如果证明所提交的信息不真实，即使产品获奖也将被取消参评资格。

Nomination is submitted by (please endorse with official company stamp):
提交人（公司印章）：

Name姓名: _____

Job title职位: _____

Signature签名: _____

Date日期: _____